


FS10VSJ-2

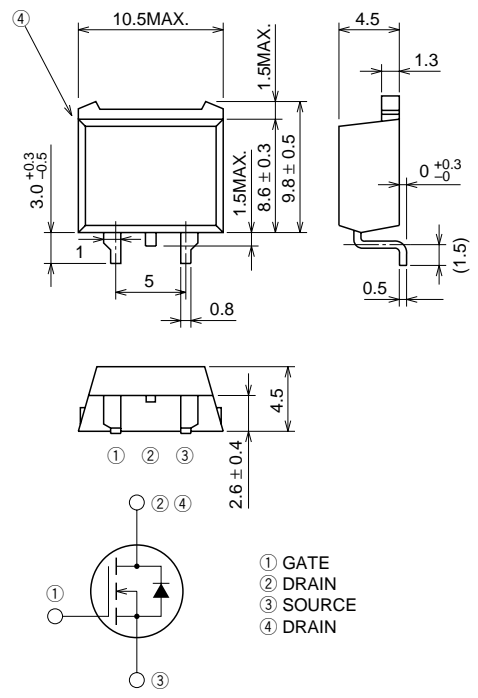
HIGH-SPEED SWITCHING USE

FS10VSJ-2



- 4V DRIVE
- V_{DSS} 100V
- $r_{DS(ON)}$ (MAX) 0.19Ω
- I_D 10A
- Integrated Fast Recovery Diode (TYP.) 95ns

OUTLINE DRAWING Dimensions in mm



① GATE
② DRAIN
③ SOURCE
④ DRAIN

TO-220S

APPLICATION

Motor control, Lamp control, Solenoid control
DC-DC converter, etc.

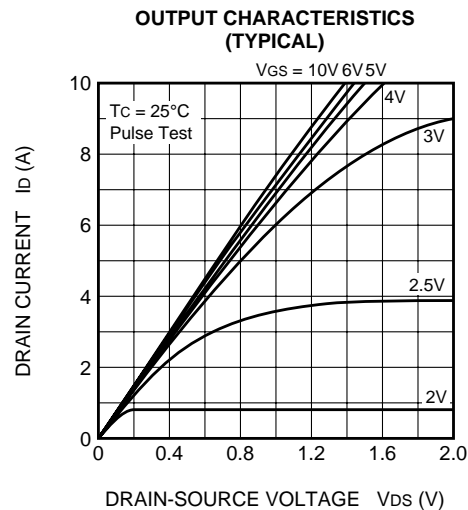
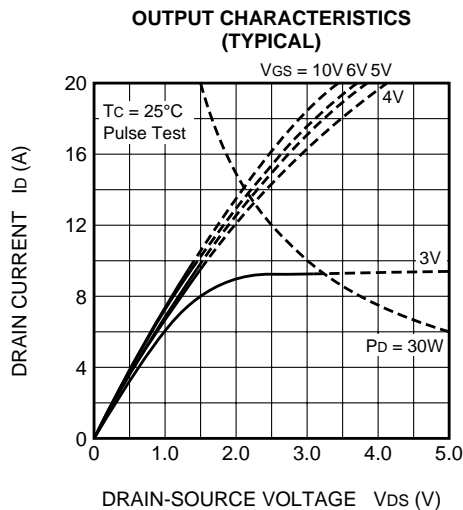
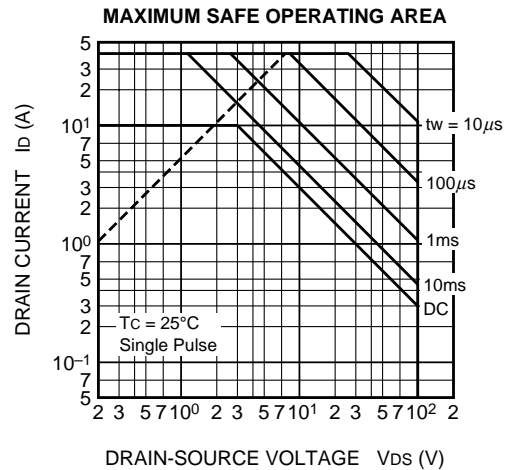
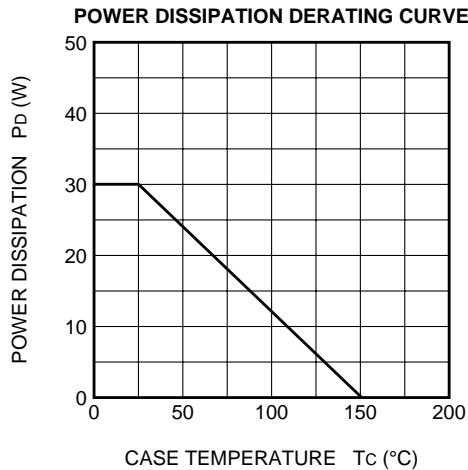
MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DSS}	Drain-source voltage	$V_{GS} = 0V$	100	V
V_{GSS}	Gate-source voltage	$V_{DS} = 0V$	± 20	V
I_D	Drain current		10	A
I_{DM}	Drain current (Pulsed)		40	A
I_{DA}	Avalanche drain current (Pulsed)	$L = 100\mu\text{H}$	10	A
I_S	Source current		10	A
I_{SM}	Source current (Pulsed)		40	A
P_D	Maximum power dissipation		30	W
T_{ch}	Channel temperature		$-55 \sim +150$	$^\circ\text{C}$
T_{stg}	Storage temperature		$-55 \sim +150$	$^\circ\text{C}$
—	Weight	Typical value	1.2	g

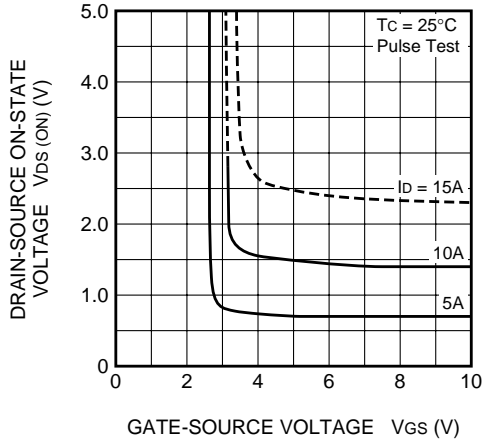
ELECTRICAL CHARACTERISTICS (Tch = 25°C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V(BR)DSS	Drain-source breakdown voltage	Id = 1mA, Vgs = 0V	100	—	—	V
IgSS	Gate-source leakage current	Vgs = ±20V, Vds = 0V	—	—	±0.1	μA
IbSS	Drain-source leakage current	Vds = 100V, Vgs = 0V	—	—	0.1	mA
VGS(th)	Gate-source threshold voltage	Id = 1mA, Vds = 10V	1.0	1.5	2.0	V
rDS(ON)	Drain-source on-state resistance	Id = 5A, Vgs = 10V	—	0.14	0.19	Ω
rDS(ON)	Drain-source on-state resistance	Id = 5A, Vgs = 4V	—	0.16	0.21	Ω
VDS(ON)	Drain-source on-state voltage	Id = 5A, Vgs = 10V	—	0.70	0.95	V
yfs	Forward transfer admittance	Id = 5A, Vds = 5V	—	13	—	S
Ciss	Input capacitance	Vds = 10V, Vgs = 0V, f = 1MHz	—	800	—	pF
Coss	Output capacitance		—	125	—	pF
Crss	Reverse transfer capacitance		—	45	—	pF
td(on)	Turn-on delay time	VDD = 50V, Id = 5A, Vgs = 10V, RGEN = RGS = 50Ω	—	14	—	ns
tr	Rise time		—	15	—	ns
td(off)	Turn-off delay time		—	65	—	ns
tf	Fall time		—	40	—	ns
VSD	Source-drain voltage	Is = 5A, Vgs = 0V	—	1.0	1.5	V
Rth(ch-c)	Thermal resistance	Channel to case	—	—	4.17	°C/W
trr	Reverse recovery time	Is = 10A, dis/dt = -100A/μs	—	95	—	ns

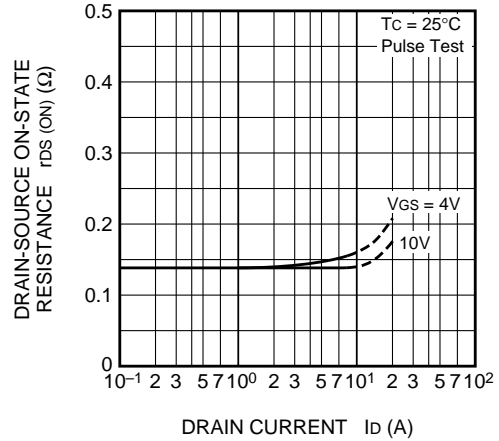
PERFORMANCE CURVES



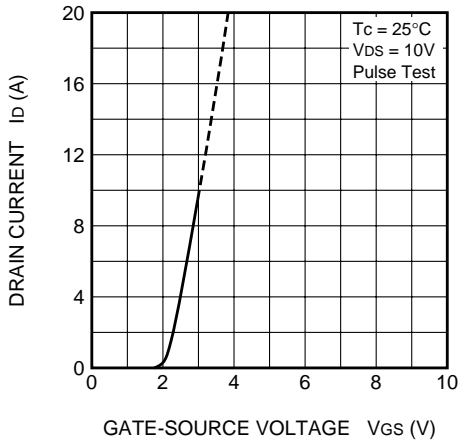
ON-STATE VOLTAGE VS. GATE-SOURCE VOLTAGE (TYPICAL)



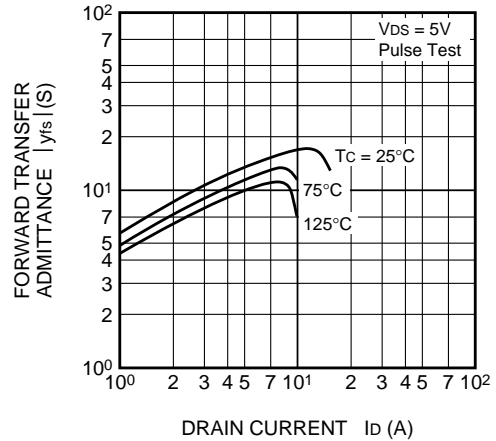
ON-STATE RESISTANCE VS. DRAIN CURRENT (TYPICAL)



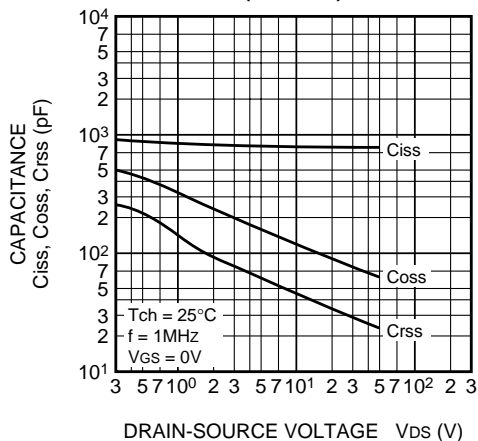
TRANSFER CHARACTERISTICS (TYPICAL)



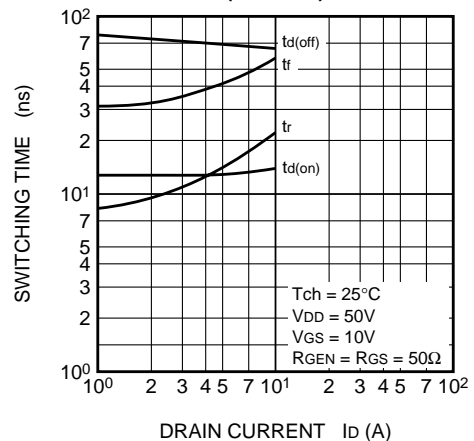
FORWARD TRANSFER ADMITTANCE VS. DRAIN CURRENT (TYPICAL)



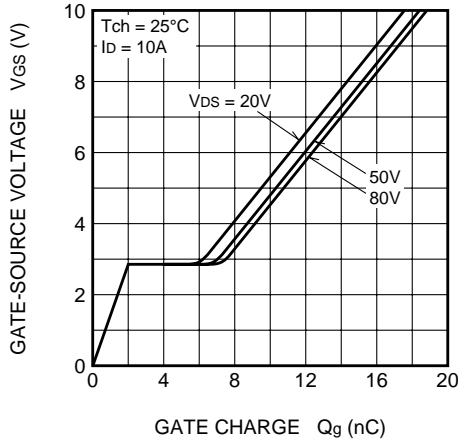
CAPACITANCE VS. DRAIN-SOURCE VOLTAGE (TYPICAL)



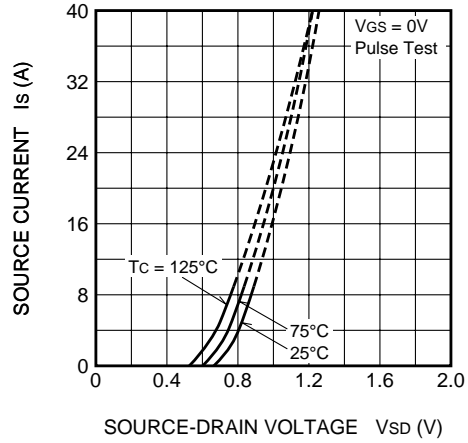
SWITCHING CHARACTERISTICS (TYPICAL)



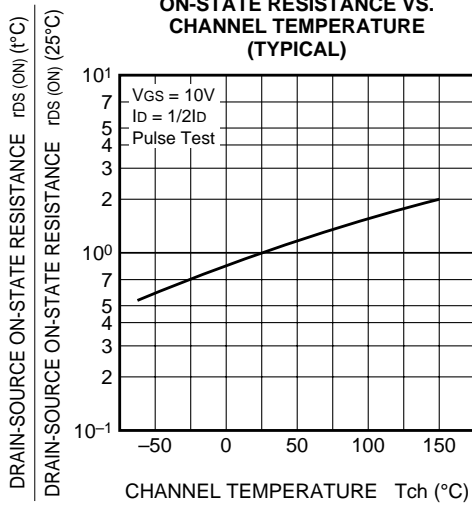
GATE-SOURCE VOLTAGE VS. GATE CHARGE (TYPICAL)



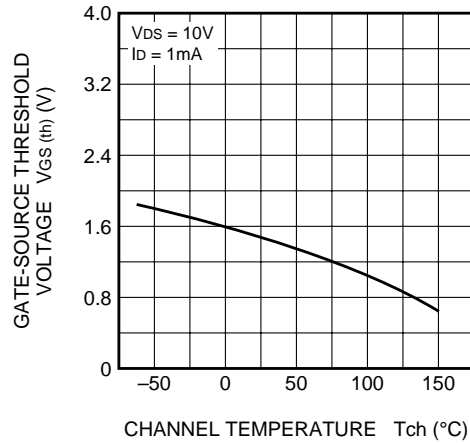
SOURCE-DRAIN DIODE FORWARD CHARACTERISTICS (TYPICAL)



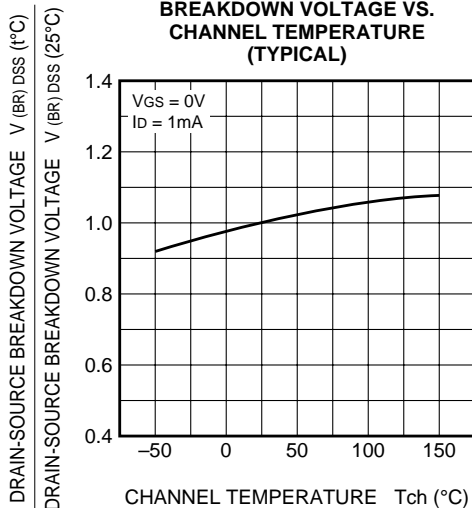
ON-STATE RESISTANCE VS. CHANNEL TEMPERATURE (TYPICAL)



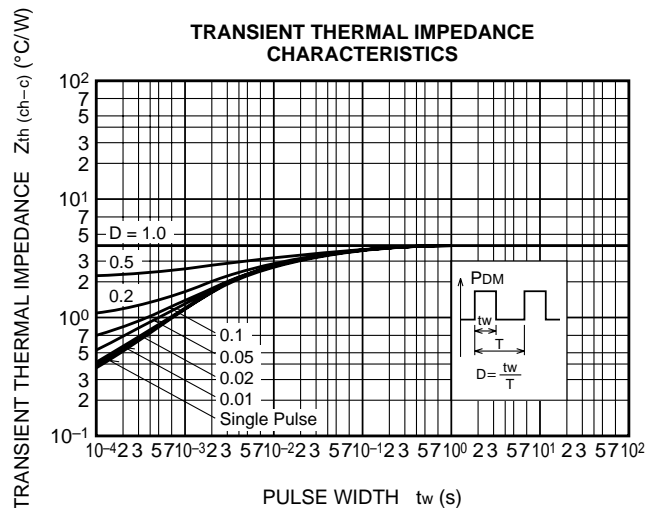
THRESHOLD VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)



BREAKDOWN VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



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Datasheets for electronics components.